



Material Content Data Sheet



Sales Product Name		BTS7200-2EPA		Issued		1. August 2018		
MA#		MA001868662						
Package		PG-TSDSO-14-22		Weight*		64.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.649	1.00	1.00	10048	10048
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		146	
	non noble metal	zinc	7440-66-6	0.038	0.06		583	
	non noble metal	iron	7439-89-6	0.754	1.17		11668	
wire	non noble metal	copper	7440-50-8	30.617	47.38	48.62	473753	486150
	non noble metal	copper	7440-50-8	0.182	0.28	0.28	2822	2822
	encapsulation	organic material	carbon black	1333-86-4	0.089	0.14		1377
encapsulation	plastics	epoxy resin	-	3.470	5.37		53688	
	inorganic material	silicondioxide	60676-86-0	26.097	40.38	45.89	403806	458871
leadfinish	non noble metal	tin	7440-31-5	1.642	2.54	2.54	25402	25402
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12627	12627
glue	plastics	epoxy resin	-	0.046	0.07		714	
	noble metal	silver	7440-22-4	0.218	0.34	0.41	3366	4080
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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